Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HP Cloud Line 2200 G3 1211R Server

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		4
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing		0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	**Tool Size (if applicable)**
Philps Driver	#1,#2

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Loose and remove two screws and click hood button and open TOP Cover.
2. Remove PSU
3. Remove HDD(in rear side if installed) and HDD in Front side.
4. Remove Riser card Module and disconnect the cable
5. Remove air duct
6. Loose the CPU Heatsink screw and remove the heatsink
7. Remove the CPU
8. Remove the Memory
9. Loose the screw and remove System Card(OCP Card ,HBA Card ,Add on Card) if installed
10. Disconnect all cable, loose the screw and remove PDB Module
11. Loose the screw and remove the Mother board
12. Remove the HDD Backplane
13. Loose the screw and remove HDD Expander card
14. Remove Fan Module
15. Loose screw and remove front panel board

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1-Remove Top Cover

Attachment 2-Remove PSU

Attachment 3-Remove HDD(in rear side if installed) and HDD in Front side.

Attachment 4-Remove Riser card Module and disconnect the cable

Attachment 5-Remove air duct

Attachment 6-Loose the CPU Heatsink screw and remove the heatsink

Attachment 7-Remove the CPU

Attachment 8-Remove the Memory

Attachment 9- Loose the screw and remove System Card(OCP Card ,HBA Card ,Add on Card) if installed

Attachment 10-Disconnect all cable, loose the screw and remove PDB Module

Attachment 11- Loose the screw and remove the Mother board.

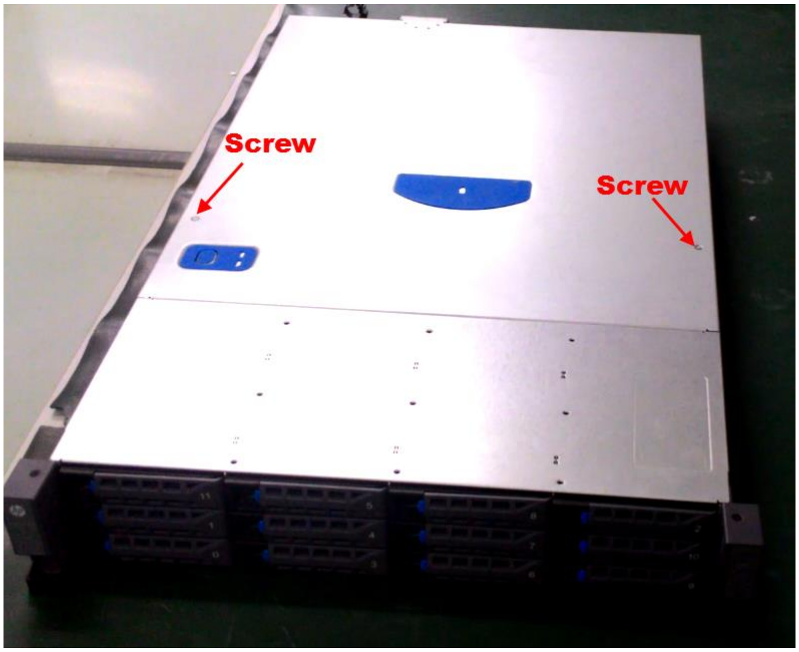
Attachment 12-Remove the HDD Backplane

Attachment 13- Loose the screw and remove HDD Expander card

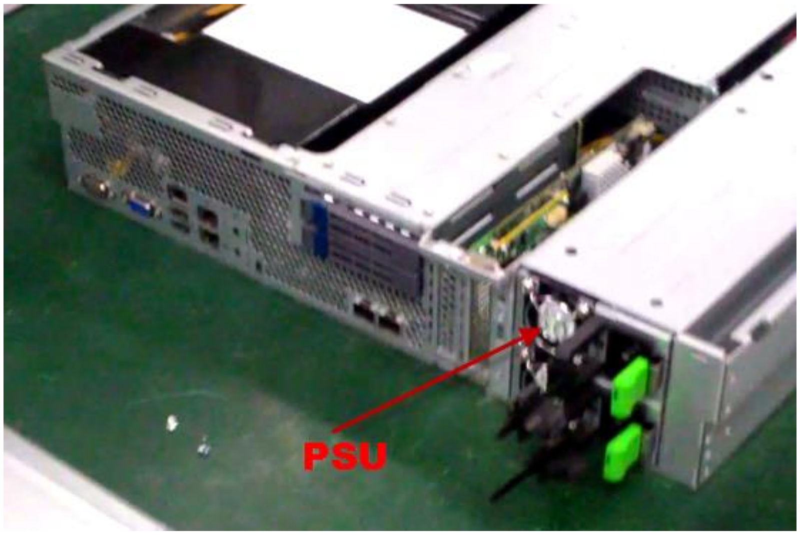
Attachment 14 -Remove Fan Module

Attachment 15 -Loose screw and remove front panel board

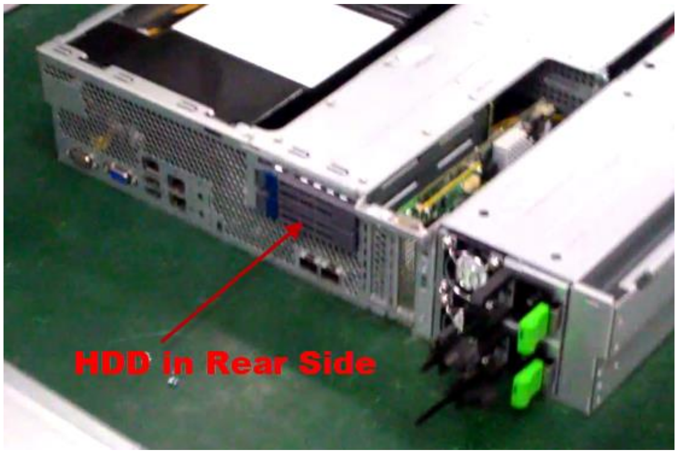
Attachment 1-Remove Top Cover

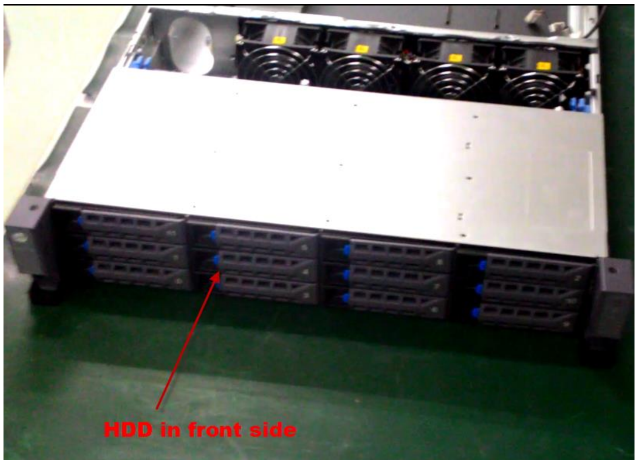


Attachment 2-Remove PSU

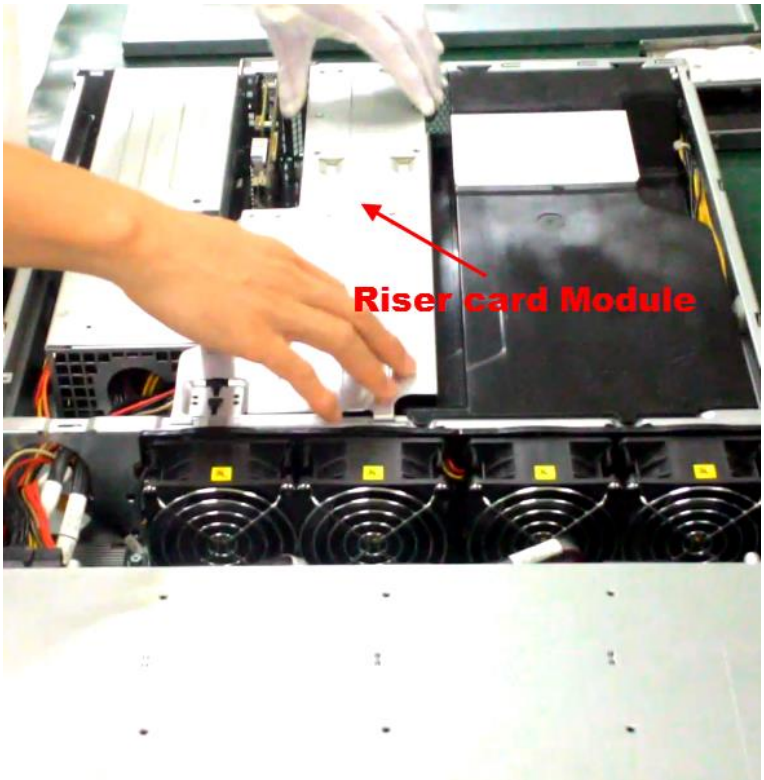


Attachment 3-Remove HDD(in rear side if installed)

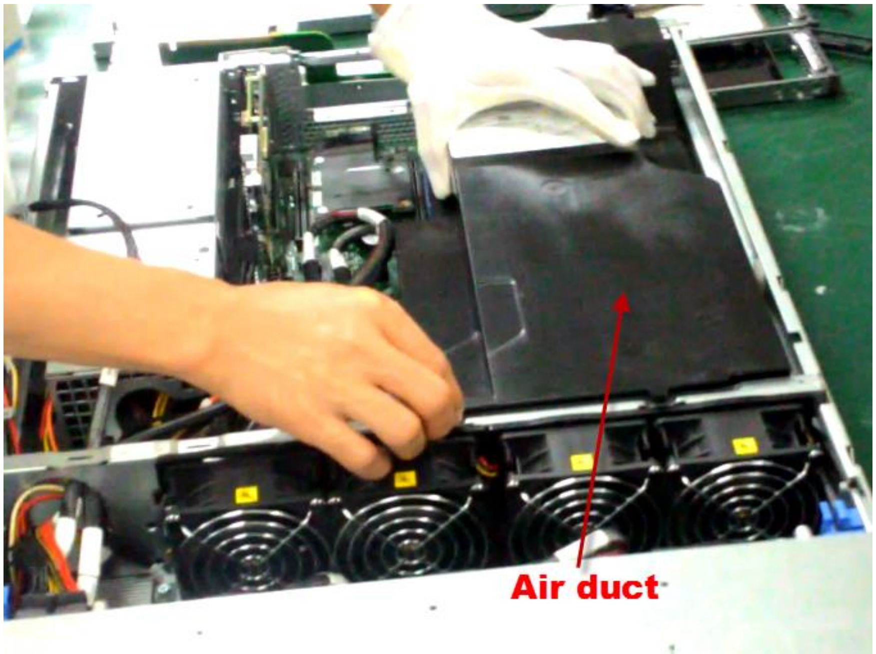




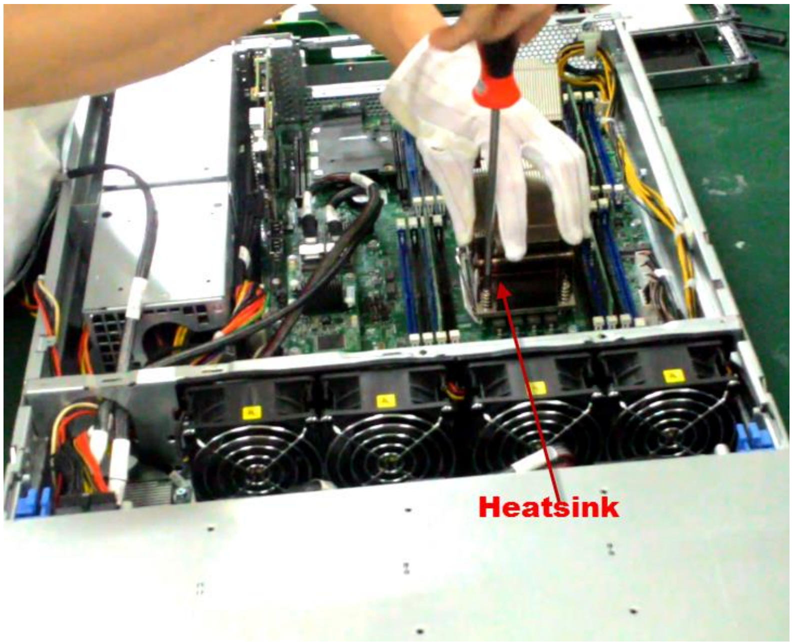
Attachment 4-Remove Riser card Module and disconnect the cable



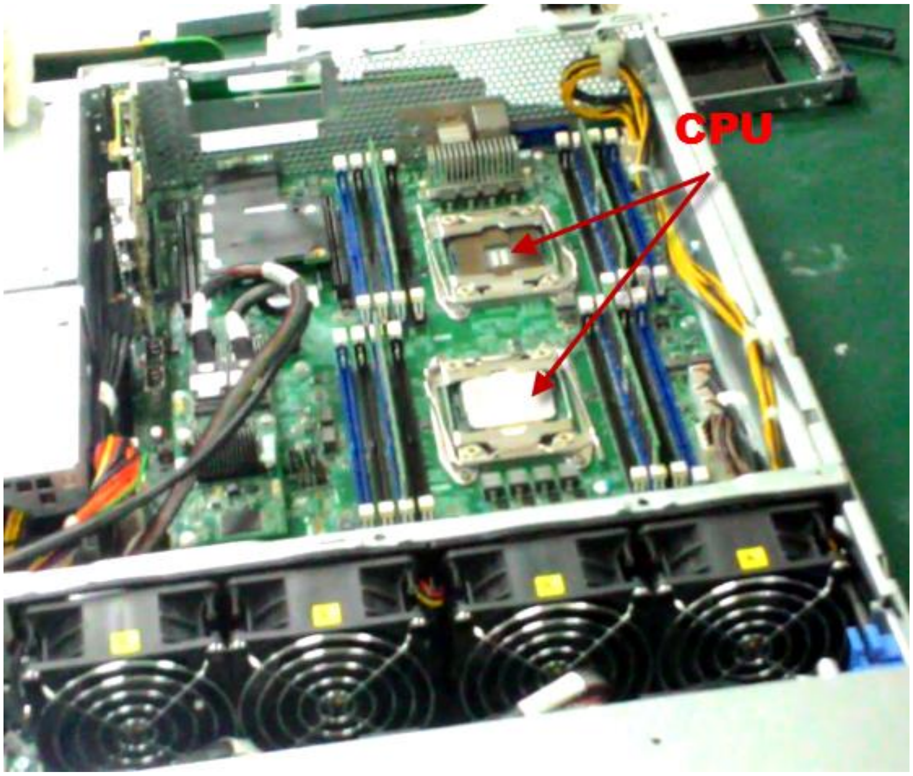
Attachment 5-Remove air duct



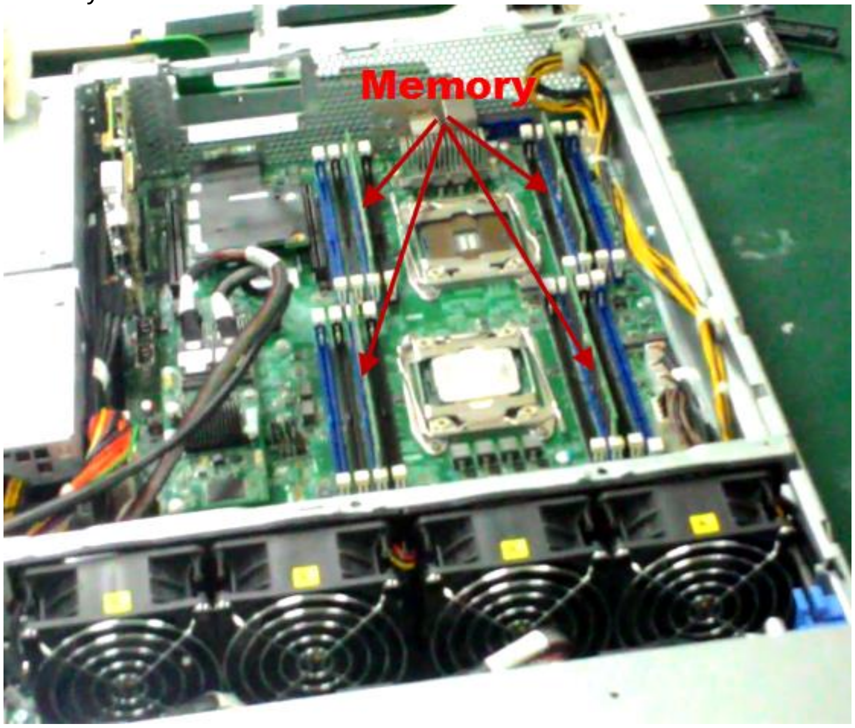
Attachment 6-Loose the CPU Heatsink screw and remove the heatsink



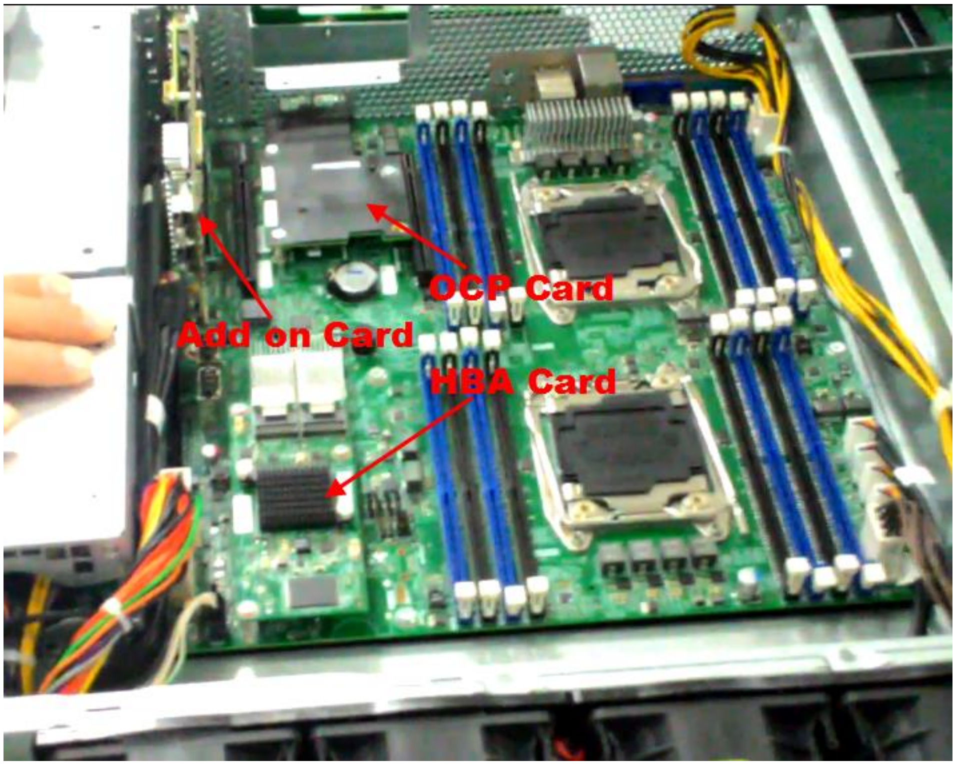
Attachment 7-Remove CPU



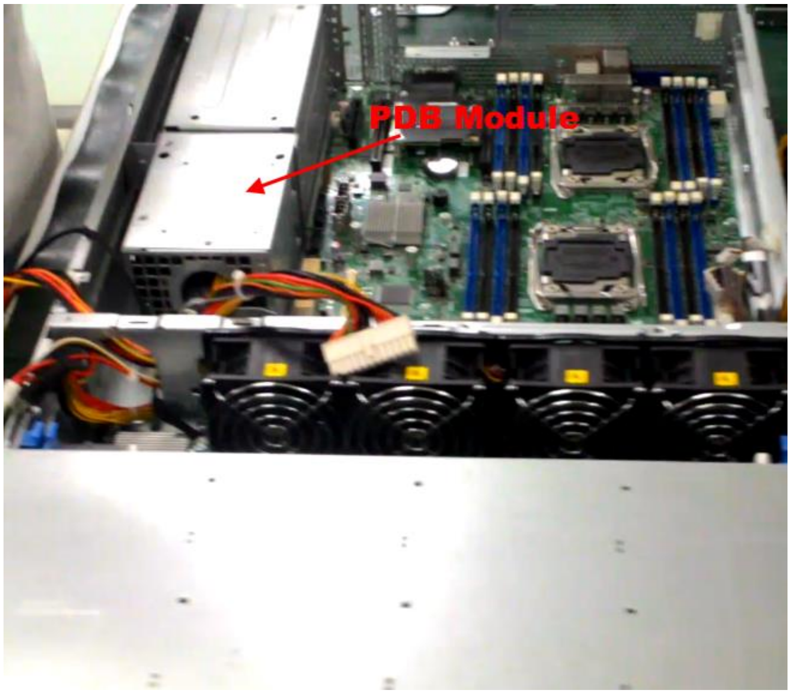
Attachment 7-Remove Memory



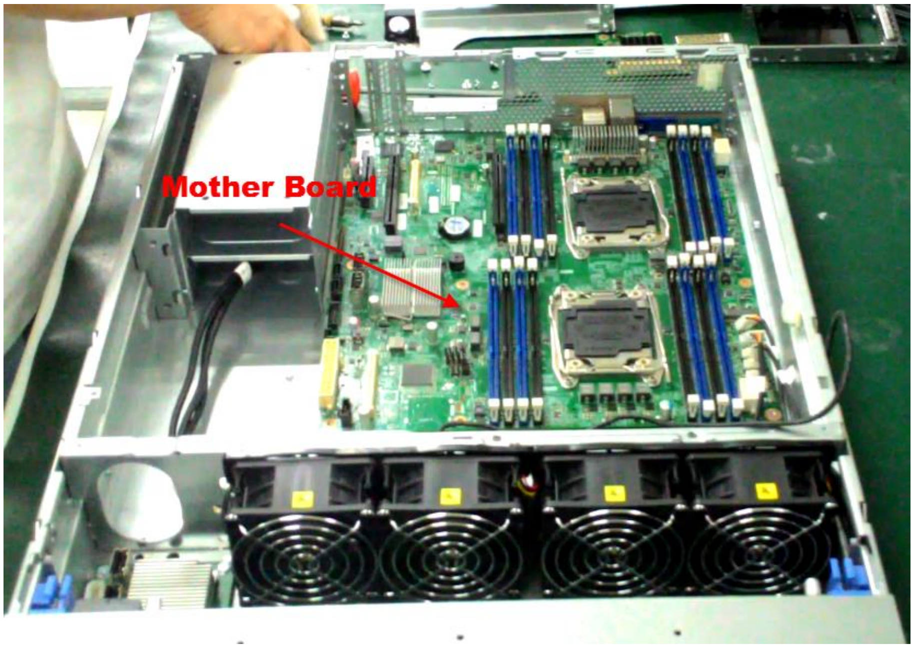
Attachment 9- Loose the screw and remove System Card(OCP Card ,HBA Card ,Add on Card) if installed



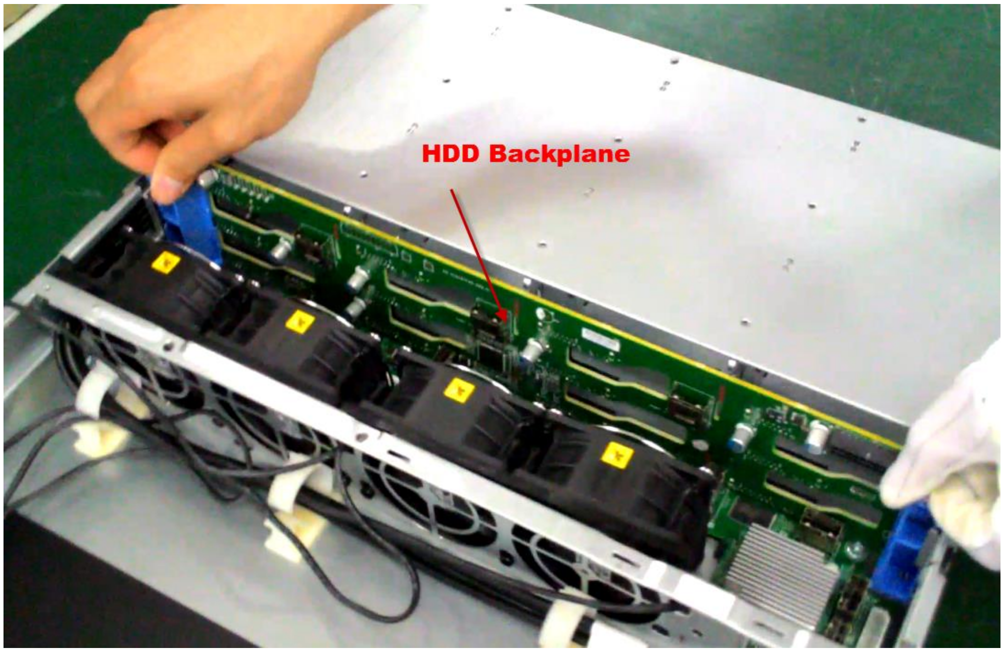
Attachment 10-Disconnect all cable, loose the screw and remove PDB Module



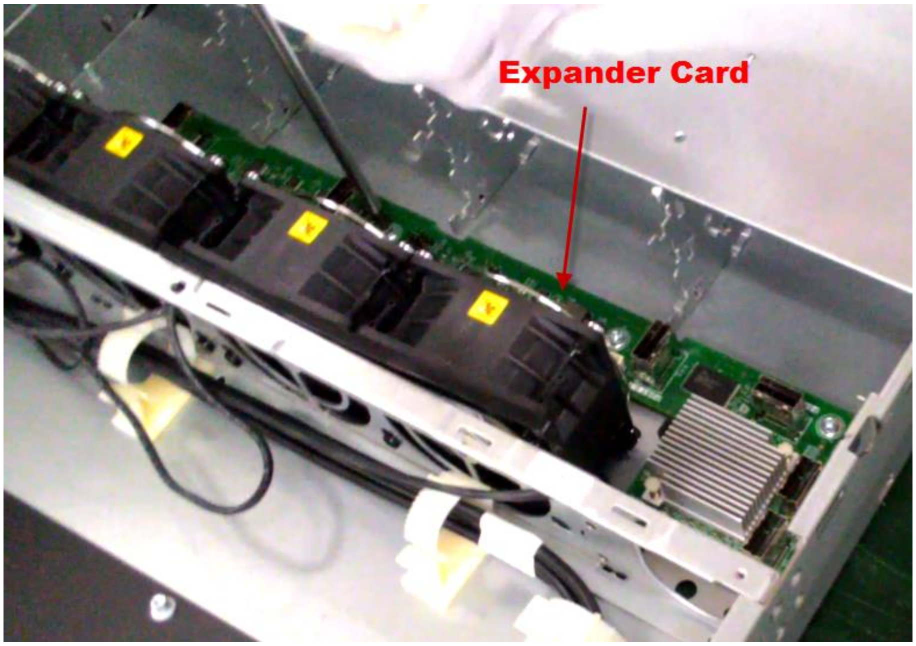
Attachment 11-Loose the screw and remove the Mother board



Attachment 12-Remove the HDD Backplane



Attachment 13- Loose the screw and remove HDD Expander card



Attachment 14 -Remove Fan Module

Attachment 15 -Loose screw and remove front panel board